

深圳市金航标电子有限公司

产品技术规格书 SPECIFICATION

| 产品型号 | PART NO: | KH3216-A35 |
|------|-------------|-------------|
| 客户料号 | CUSTOMER PA | ART NO: |
| 客户确认 | CUSTOMER AF | PPROVED BY: |
| 确认日期 | APPROVED DA | TE: |
| | | |

RoHS Compliant Parts

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| 审核 Checked by: | | 批准 Approved by: | |
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| 送样日期 Formed On | | 产品版本 Document Version | |
| | | (V1.2) | |
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产品规格书版本更改记录

Version rejigger track record

| 版本号 Version | 更改记录 Rejigger | 拟制 Prepared | 批准 Approve | 日期 Date |
|----------------|---------------------|----------------|---------------|--------------|
| V1.0 | 首次发行 | 姚富鑫 | 贺俊驹 | 2015. 12. 25 |
| V1.1 | 更改产品尺寸公差值 | 陈星 | 贺俊驹 | 2017. 05. 24 |
| V1.2 | 修正可靠性试验说明内容 8.1~8.4 | 姚富鑫 | 贺俊驹 | 2017. 11. 07 |
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备注:

- 1、更改产品电性能指标时,版本号需更换(V1.0换为V2.0、V3.0·····);
- 2、更改产品测试方法(包括可靠性测试条件),或更改使用条件时,当前版本号加系列(V1.0 换为 V1.1、V1.2……)。

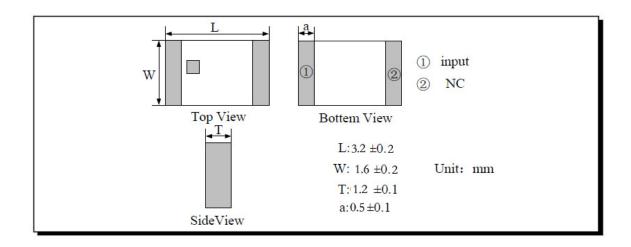


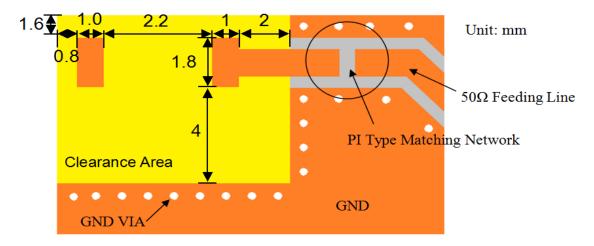
1. 概述 INTRODUCTION

金航标微波多层陶瓷天线 LA 系列产品设计用于 WLAN、WiFi、蓝牙、PHS, 手机多频天线, FM 等小体积 SMD 片式设计。

kinghelm Microwave Multi-Layer Ceramic Antenna LA series are designed to be used in WLAN, WiFi, Bluetooth, PHS, Multiple-band Mobile phone antenna, FM, etc and compact size SMD chip design.

2. 外型尺寸 Dimensions (Unit: r

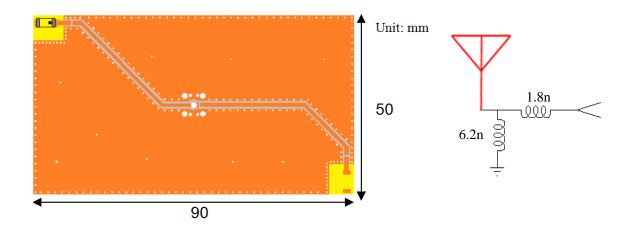








3. 测试电路和匹配电路 Evaluation Board and Matching Circuits



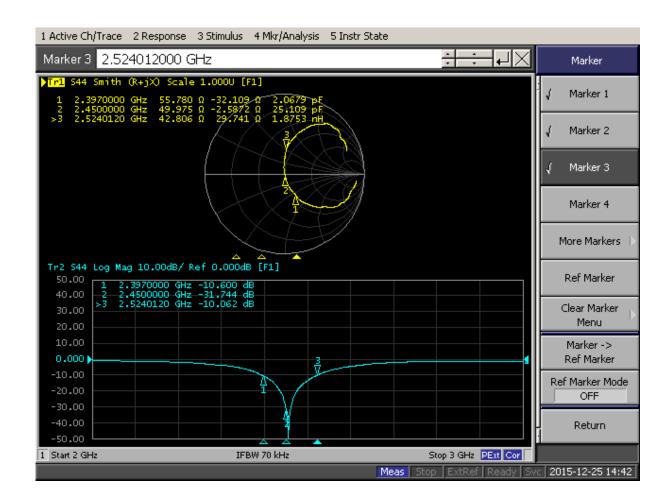
4. 电气性能 Electrical Characteristics

| No. | Item (项目) | Specifications (特性) |
|-----|-------------------------------------|---------------------|
| | Central Frequency 中心频率(No matching) | 2875MHz |
| 4.1 | (带匹配电路测试)After Matching | 2450 MHz |
| 4.2 | Band Width 通带宽度 | 100MHz typ. |
| 4.3 | Peak Gain 峰值增益 | 5.19 dBi |
| 4.4 | V.S.W.R 驻波比 | ≤2.0 |
| 4.5 | Polarization 极化方式 | Linear 线性 |
| 4.6 | Azimuth Beam width 方位角 | Omni-directional 全向 |
| 4.7 | Impedance 阻抗 | 50 Ω |



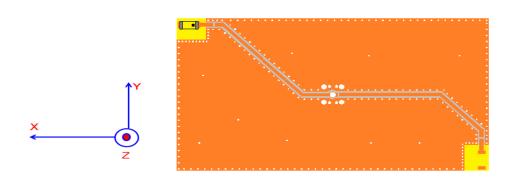


5. 特性曲线 Characteristic curve



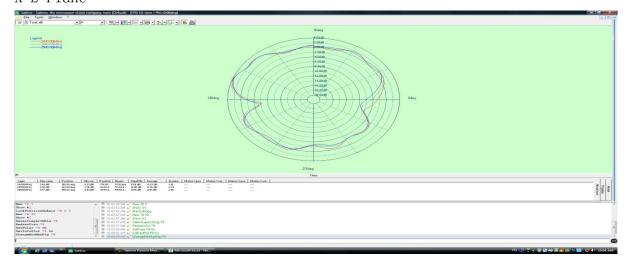
6. 方向图 Radiation Pattern

coordinates:

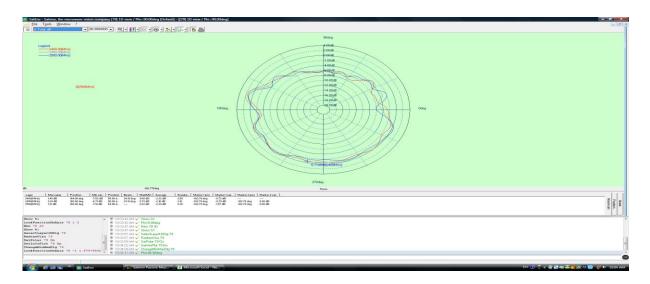




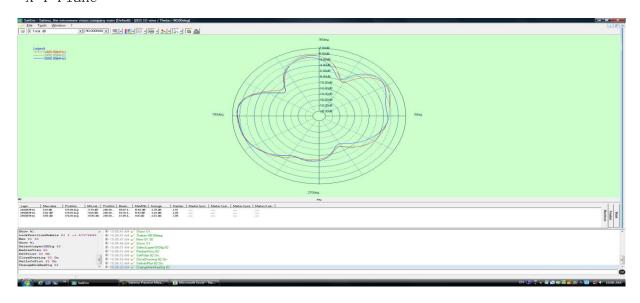
X-Z Plane



Y-Z Plane

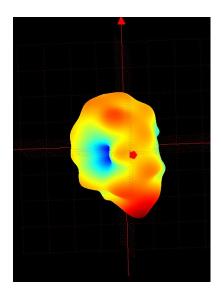


X-Y Plane





3D Radiation Pattern



| Frequency (MHz) | 2400 | 2450 | 2500 |
|--------------------|-------|-------|-------|
| Avg. Gain (dBi) | -0.23 | -0.36 | -0.51 |
| Peck Gain (dBi) | 4.98 | 5.19 | 4.55 |
| Efficiency (%) | 70 | 71.2 | 69 |



7. 可靠性试验后允许误差 Post Dependability Tolerance

经可靠性试验后允许比起始读数偏差见下表

Post Dependability Tolerance (Refer to the table)

| No. | Item (项目) | Post Dependability Tolerance (可靠性试验后允许附加误差) |
|-----|------------------------|---|
| 7.1 | Central Frequency 中心频率 | ±5 MHz |
| 7.2 | Band Width 通带宽度 | ±5 MHz |
| 7.3 | Gain 增益 | $\pm 0.1~\mathrm{dBi}$ |
| 7.4 | V.S.W.R (in BW) 驻波比 | ±0.1 |

8. 可靠性试验 Dependability Test

基准条件: 温度范围 Temperature range 25±5℃

相对湿度范围 Relative Humidity range 55~75%RH

工作温度 Operating Temperature range -40°C~+85°C

8.1 耐振动 Vibration Resist

在振动频率为 10~55Hz 振幅为 1.5mm 沿 X.Y.Z 方向各振动 2 小时后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph $8.1 \sim 8.4$ after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

8.2 耐跌落冲击 Drop Shock

在 100cm 高度处按 X, Y, Z 三个面分别自由跌落在木制地板上共 3 次后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

8.3 耐焊接热 Solder Heat Proof

能承受经 $120\sim150^{\circ}$ C的温度预热 120 秒后,在 255° C+ 10° C的焊锡浸 5 ± 0.5 秒,或 300° C- 10° C的 电烙铁焊接 3 ± 0.5 秒,焊接面无损伤。

The device should be satisfied after preheating at $120^{\circ}\text{C} \sim 150^{\circ}\text{C}$ for 120 seconds and dipping in soldering Sn at $255^{\circ}\text{C} + 10^{\circ}\text{C}$ for 5 ± 0.5 seconds, or electric iron $300^{\circ}\text{C} - 10^{\circ}\text{C}$ for 3 ± 0.5 seconds, without damnify.

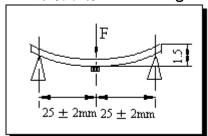
8.4 结合力试验 Tensile Strength of Terminal

在产品电极端子上或表面上应能承受 1kg 垂直拉力 10±1 秒。

The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10 ± 1 seconds.

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8.5 耐弯曲试验 Bending Resist Test



将产品按图焊在 1.6 ± 0.2 mm 的 PCB 板中间,由箭头方向施力: 1 mm/S,弯曲距离: 1.5 mm,保持 5 ± 1S,产品金属层无脱落。

Weld the product to the center part of the PCB with the thickness $1.6\pm0.2\text{mm}$ as the illustration shows, and keep exerting force arrow-ward on it at speed of :1mm/S , and hold for $5\pm1S$ at the position of 1.5mm bending distance , so far , any peeling off of the

product metal coating should not be detected.

8.6 耐湿热特性 Moisture Proof

在温度为 $60\pm2^{\circ}$ C,相对湿度 $90\sim95\%$ 的恒温湿箱中放置 96 小时,在常温中恢复 $1\sim2$ 小时后测试、符合表 $8.1\sim8.4$ 规定。

The device should satisfy the electrical characteristics specified in paragraph $8.1 \sim 8.4$ after exposed to the temperature 60 ± 2 °C and the relative humidity $90 \sim 95\%$ RH for 96 hours and $1 \sim 2$ hours recovery time under normal condition.

8.7 高温特性 High Temperature Endurance

在温度为 85 ± 5 °C的恒温箱中放置 96 ± 2 小时,在常温中恢复 1~2 小时后测试。符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph $8.1 \sim 8.4$ after exposed to temperature 85 ± 5 °C for 96 ± 2 hours and $1 \sim 2$ hours recovery time under normal temperature.

8.8 低温特性 Low Temperature Endurance

在温度为-40℃±5℃低温箱中放置 96±2 小时后恢复 1~2 小时测试符合表 8.1~8.4 规定。

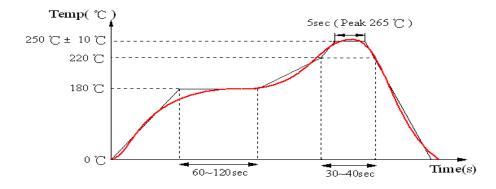
The device should also satisfy the electrical characteristics specified in paragraph $8.1 \sim 8.4$ after exposed to the temperature $-40\% \pm 5\%$ for 96 ± 2 hours and to 2 hours recovery time under normal temperature.

8.9 温度循环 Temperature Cycle Test

在-40°C温度中保持 30 分钟, 再在+85°C温度中保持 30 分钟, 共循环 5 次后在常温中恢复 1~2 小时后测试符合表 8.1~8.4 规定。

The device should also satisfy the electrical characteristics specified in paragraph $8.1 \sim 8.4$ after exposed to the low temperature -40°C and high temperature $+85^{\circ}\text{C}$ for 30 ± 2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

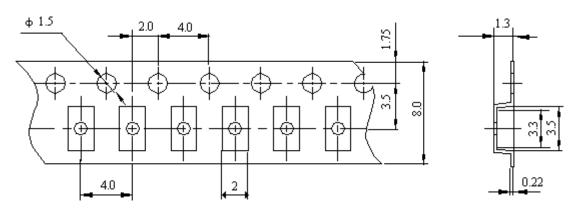
9. 回流焊温度 Reflow Soldering Standard Condition





10 包装尺寸(3216) Packaging and Dimensions

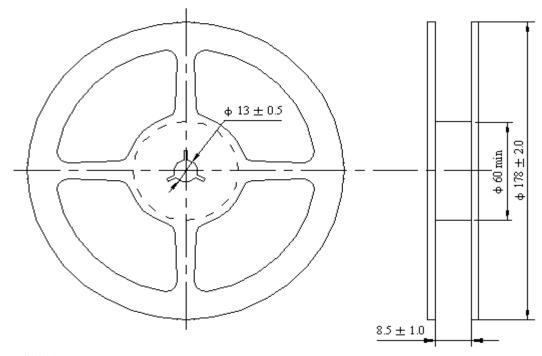
10.1 Plastic Tape



包装说明: Remarks for Package

载带尾部空穴长度 150~200mm,载带头部空穴长度 250~300mm,头部的盖带加长 250mm。 Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.

10.2 Reel (3000 pcs/Reel)



10.3 储存条件 Storage Period

易氧化产品,真空状态储存一年.产品拆封后请于168小时内用完或重新密封包装!

Oxidizable, 12 months in vacuum sealed bag . Material, please repack within 168 hours by re-seal the package treatment after use them!

储存温度与湿度:

Storage Temperature Range: <30 degree C, Humidity: <60%RH

